

General Description

The SA21308B is a 500mA current linear regulator featuring ultra-low ground current and low dropout voltage.

The device offers an adjustable output voltage with $\pm 1\%$ reference accuracy over temperature. It also includes comprehensive protection features including over current limiting, short circuit protection, and over-temperature operation.

The SA21308B is available in a compact DFN2×2-6 package.

Applications

- Infotainment Power Supplies
- Automotive Cluster Displays
- Cameras
- Telematics Control Units
- General Purpose Automotive

Features

- Input Voltage Range: 2V to 6V
- Adjustable Output Voltage: 0.55V to 5.5V
- Low Dropout Voltage: 110mV (Typ.) at 500mA (3.3V V_{OUT})
- Power Supply Rejection Ratio (PSRR): 55dB @ 1kHz
- Output Accuracy:
 - $\pm 0.85\%$ at 25°C
 - $\pm 1\%$ from -40°C to 125°C
- Stable with a Minimum of 2.2μF or Larger Ceramic Output Capacitor
- Low Current Consumption: Typical 25μA Quiescent and 0.1μA in Shutdown
- Over Current Limit and Short Circuit Protection
- Over Temperature Protection with Auto Recovery
- Moisture Sensitivity Level (MSL): 1
- Compact DFN2×2-6 Package
- Automotive AEC-Q100 Grade 1 Qualified

Typical Application

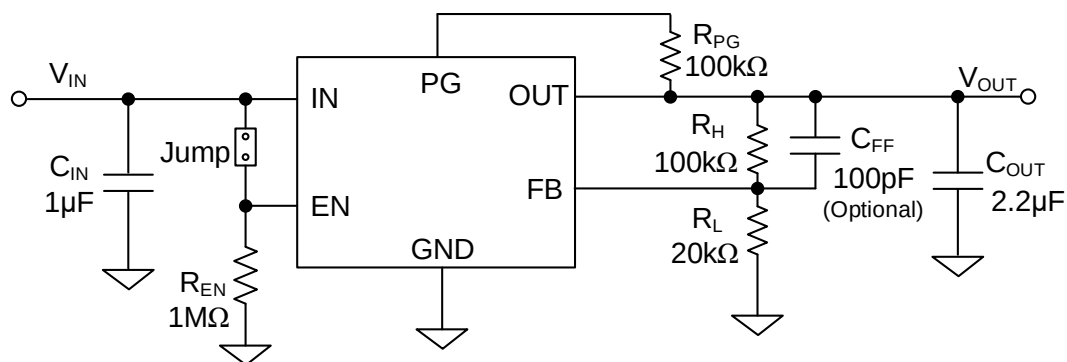


Figure 1. Typical Application Schematic

Ordering Information

SA21308□□□(□□□)

Package Code

Output Voltage Code

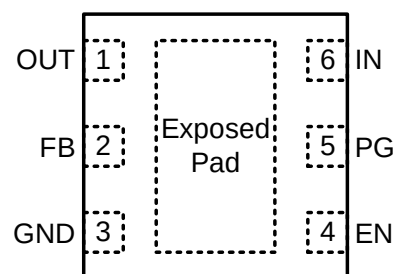
Optional Spec Code

Ordering Part Number	Output Version	Package Type	Top Mark
SA21308B00DED	Adjustable	DFN2×2-6 (RoHS Compliant and Halogen Free)	HGBxyz

Device code: HGB

x=year code, y=week code, z= lot number code

Pinout (Top View)



DFN2×2-6

Pin Description

Pin No.	Pin Name	Description
1	OUT	Output voltage pin. Decouple this pin to GND with a minimum 2.2μF ceramic capacitor.
2	FB	Feedback pin. This pin is the input to the control loop error amplifier and is used to set the output voltage of the device.
3	GND	Device GND. Connect to the device thermal pad.
4	EN	Enable pin. This pin turns the LDO on and off. If $V_{EN} \geq V_{EN(HI)}$, the regulator is enabled. If $V_{EN} \leq V_{EN(LO)}$, the regulator is disabled. The EN pin must be connected to IN if the enable function is not used.
5	PG	Open-drain power-good indicator pin for the LDO output voltage. A 10kΩ to 100kΩ external pull-up resistor is required. This pin can be left floating or connected to GND if not used.
6	IN	Input pin. Decouple this pin to GND with a recommended 1μF or larger ceramic capacitor.
Exposed Pad		The exposed pad is electrically connected to GND. Connect a GND plane or large copper area for improved thermal performance.

Block Diagram

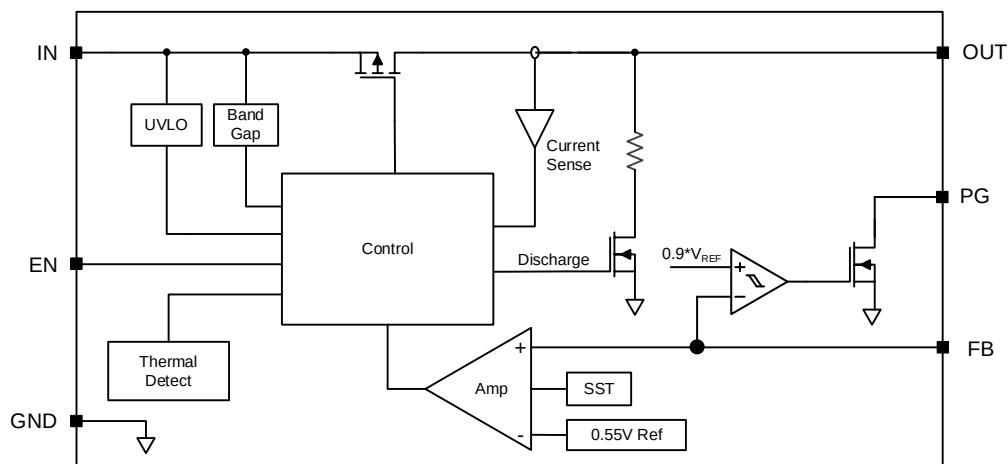


Figure 2. Block Diagram

Absolute Maximum Ratings

Parameter (Note 1)		Min	Max	Unit
IN, EN, PG, OUT		-0.3	6.5	V
FB		-0.3	2	
Junction Temperature, Operating		-40	150	°C
Lead Temperature (Soldering, 10s)			260	
Storage Temperature		-65	150	
VESD Electrostatic Discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001		±2000	V
	Charged-device model (CDM), per JEDEC specification JESD22-C101		±750	

Thermal Information

Parameter (Note 2)		Typ	Unit
θ_{JA} Junction to Ambient Thermal Resistance		68.0	°C/W
$\theta_{JC, Top}$ Junction to Top of the Case Thermal Resistance		47.8	
$\theta_{JC, Bot}$ Junction to Bottom of the Case Thermal Resistance		14.1	
Pd Power Dissipation $T_A = 25^\circ\text{C}$		1.83	W

Recommended Operating Conditions

Parameter (Note 3)		Min	Max	Unit
IN		2	6	V
OUT		0.55	5.5	
Output Current		0.001	0.5	A
Ambient Temperature, Range		-40	125	°C

Electrical Characteristics

($V_{IN}=V_{OUT(NOM)}+0.5V$ or $2V$ (which is greater), $I_{OUT}=1mA$, $V_{EN}=V_{IN}$, $C_{IN}=1\mu F$, $C_{OUT}=2.2\mu F$, $T_J = -40^{\circ}C \sim 125^{\circ}C$, unless otherwise specified, all typical values are at $T_J=25^{\circ}C$ (Note 4)).

Parameter		Symbol	Test Conditions	Min	Typ	Max	Unit
Input	Voltage	V _{IN}		2		6	V
	UVLO, rising	V _{ULVO, rising}	V _{IN} rising		1.75	2.00	V
	UVLO, falling	V _{ULVO, falling}	V _{IN} falling		1.70	1.95	
	UVLO Hysteresis	V _{UVLO_HYS}	V _{IN} hysteresis		50		mV
	Shutdown Current	I _{SHDN}	V _{EN} =0V, -40℃ ≤ T _J ≤ 125℃		0.1	1.5	μA
	Ground Current	I _{GND}	I _{OUT} =0mA, T _J =25℃			50	μA
I _{OUT} =0mA, -40℃ ≤ T _J ≤ 125℃				25	55		
Output	Voltage	V _{OUT}		0.55		5.5	V
	Output Accuracy (Note 6)	V _{OUT_ACC}	T _J =25℃	-0.85		0.85	%
			-40℃ ≤ T _J ≤ 125℃	-1		1	
	Line Regulation	ΔV _{LNR}	V _{OUT(NOM)} +0.5V≤V _{IN} ≤6V		2	7.5	mV
Load Regulation	ΔV _{LDR}	V _{IN} ≥2.0V, 0.1mA≤I _{OUT} ≤0.5A			0.03		V/A
Feedback	Voltage	V _{FB}			0.55		V
	Feedback Pin Current	I _{FB}			0.01	0.1	μA
Enable	High Voltage	V _{EN(HI)}		1.1			V
	Low Voltage	V _{EN(LO)}				0.3	
	Enable Pin Current	I _{EN}	V _{IN} =V _{EN} =6V			10	
Current Limit	Output Current Limit	I _{CL}	V _{IN} =2V, V _{OUT(NOM)} <1V, V _{OUT} =V _{OUT(NOM)} -0.2V; V _{IN} =V _{OUT(NOM)} +1V, V _{OUT(NOM)} ≥1V, V _{OUT} = V _{OUT(NOM)} ×0.85	500	850	1200	mA
	Short-Circuit Current Limit	I _{SC}	V _{IN} =2V, V _{OUT(NOM)} <1V, V _{OUT} =0V; V _{IN} =V _{OUT(NOM)} +1V, V _{OUT(NOM)} ≥1V, V _{OUT} =0V	180	300	450	mA
Power Good	High Threshold	PG _{HTH}	V _{OUT} increasing	88	92	96	%V _{OUT}
	Low Threshold	PG _{LT} H	V _{OUT} decreasing	85	90	94	%V _{OUT}
	Hysteresis	PG _{HYST}			2		%V _{OUT}
	PG Pin Low-Level Output Voltage	V _{OL(PG)}	V _{IN} ≥2.75V, I _{SINK} =2.0mA			300	mV
	Leakage Current	I _{lkg(PG)}	V _{OUT} >PG _{HTH} , V _{PG} =6V		7	50	nA
	PG Delay Time Rising	t _{PGDH}	Time from 92% V _{OUT} to 20% of PG	40	165	290	μs
	PG Delay Time Falling	t _{PGDL}	Time from 90% V _{OUT} to 80% of PG		7		μs

Electrical Characteristics (Cont.)

(($V_{IN}=V_{OUT(NOM)}+0.5V$ or $2V$ (which is greater), $I_{OUT}=1mA$, $V_{EN}=V_{IN}$, $C_{IN}=1\mu F$, $C_{OUT}=2.2\mu F$, $T_J = -40^{\circ}C\sim 125^{\circ}C$, unless otherwise specified, all typical values are at $T_J=25^{\circ}C$ (Note 4)).

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Dropout Voltage	ΔV_{DROP}	$I_{OUT}=500mA, V_{OUT}=0.95\times V_{OUT(NOM)}, 2V\leq V_{OUT}<2.5V$		160	250	mV
		$I_{OUT}=500mA, V_{OUT}=0.95\times V_{OUT(NOM)}, 2.5V\leq V_{OUT}<3.3V$		120	210	mV
		$I_{OUT}=500mA, V_{OUT}=0.95\times V_{OUT(NOM)}, 3.3V\leq V_{OUT}\leq 5.5V$		110	185	mV
Startup Time	t_{STR}	From EN low-to-high transition to $V_{OUT}=V_{OUT(NOM)}\times 0.95$	200	500	850	μs
Power Supply Rejection Ratio (Note 5)	PSRR	$V_{IN}=2.8V, V_{OUT}=1.8V, I_{OUT}=500mA, f=1kHz$		55		dB
		$V_{IN}=2.8V, V_{OUT}=1.8V, I_{OUT}=500mA, f=100kHz$		35		dB
		$V_{IN}=2.8V, V_{OUT}=1.8V, I_{OUT}=500mA, f=1MHz$		30		dB
Pull Down Resistance	$R_{PULLDOWN}$	$V_{IN}=6V, V_{EN}=0V$		95		Ω
Thermal Shutdown Temperature (Note 5)	T_{SD}			170		$^{\circ}C$
Thermal Shutdown Reset (Note 5)	T_{Reset}			155		$^{\circ}C$

Note 1: Stresses beyond the “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note 2: Measured with natural convection at $T_A = 25^{\circ}C$ on a thermal conductivity test board with vias based on JEDEC 51-5,7.

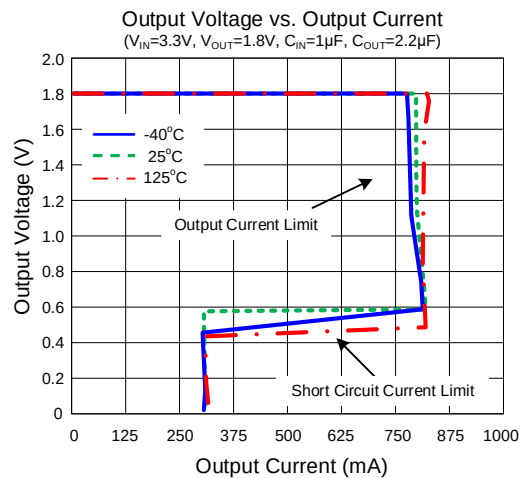
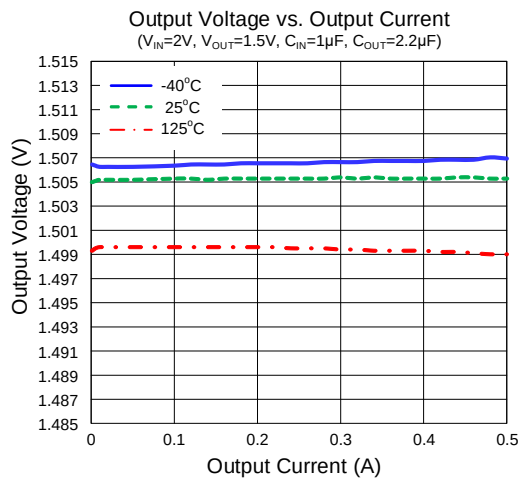
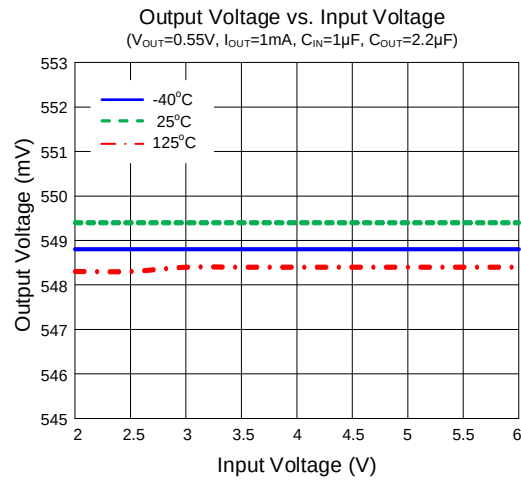
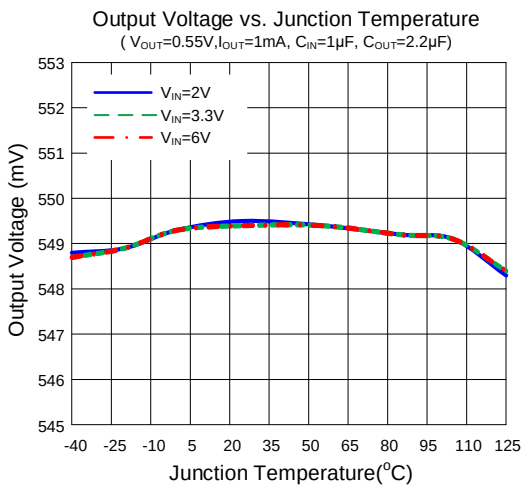
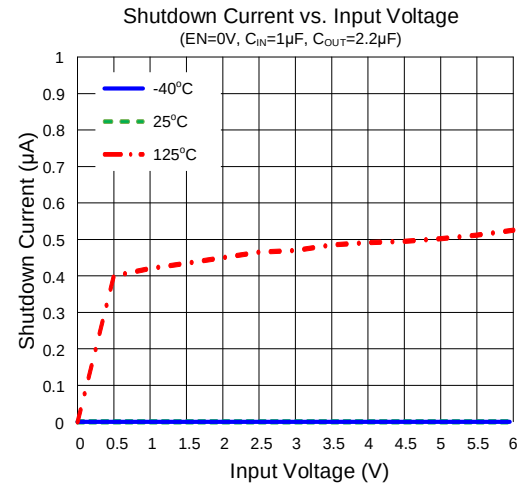
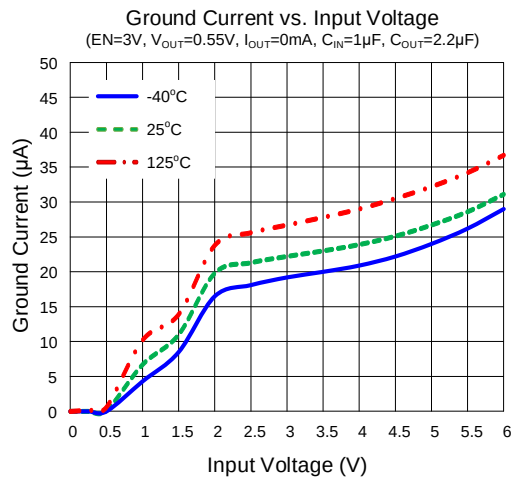
Note 3: The device is not guaranteed to function outside its operating conditions.

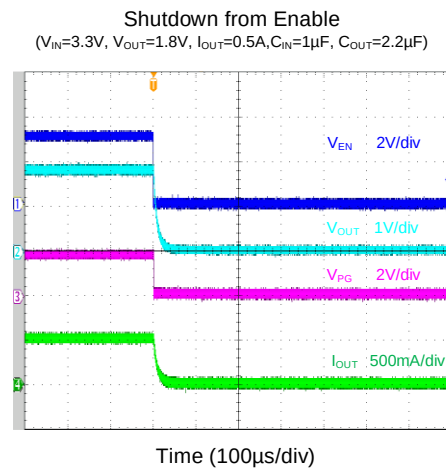
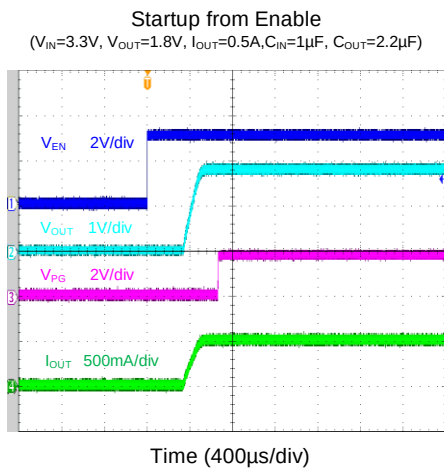
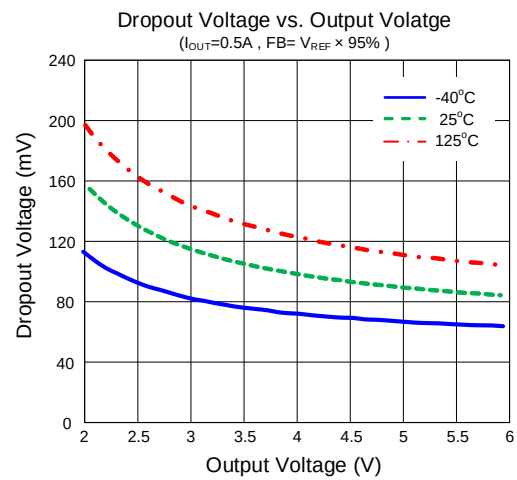
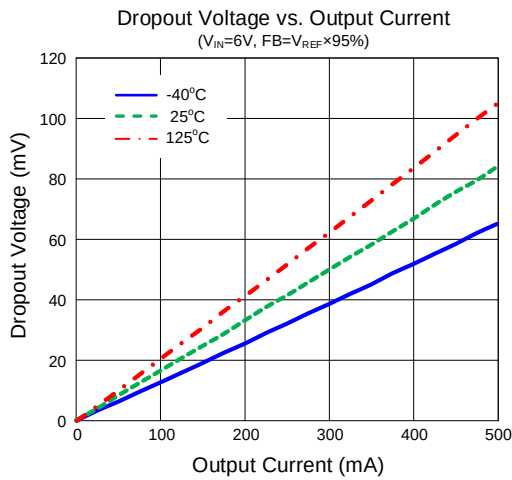
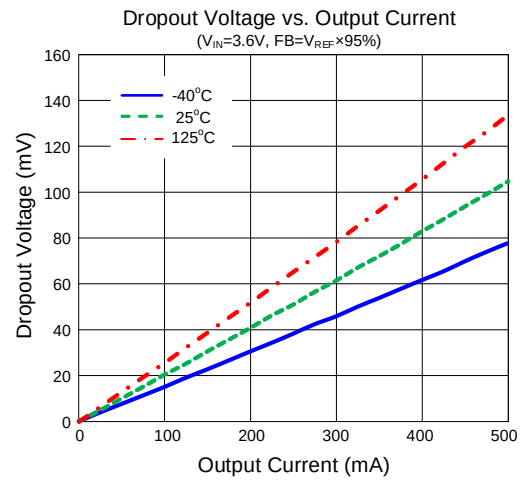
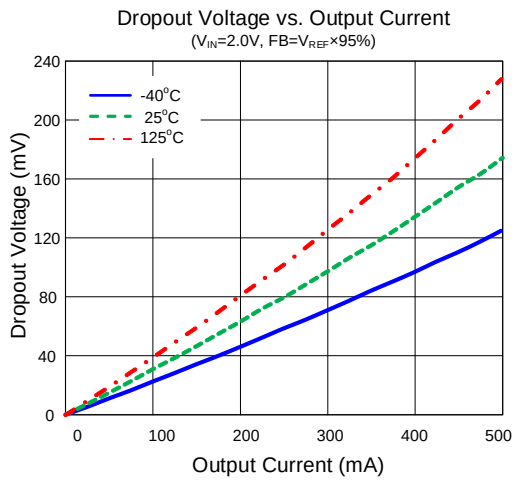
Note 4: Unless otherwise stated, limits are 100% production tested under pulsed load conditions such that $T_A \cong T_J = 25^{\circ}C$. Limits over the operating temperature range (see recommended operating conditions) and relevant voltage range(s) are guaranteed by design, test, or statistical correlation.

Note 5: Guaranteed by design or statistical correlation and not production tested.

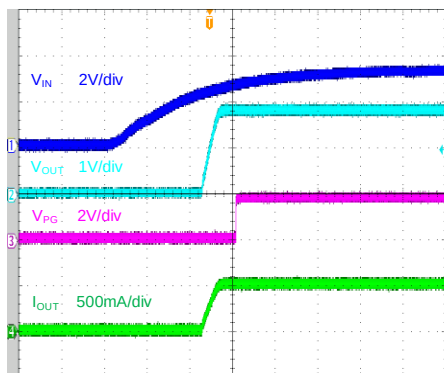
Note 6: Tolerances of the external feedback resistors are not considered.

Typical Performance Characteristics



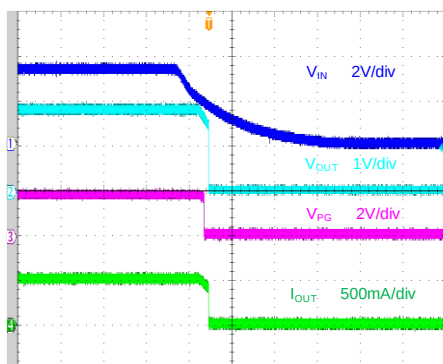


Startup from V_{IN}
($V_{IN}=V_{EN}=3.3V$, $V_{OUT}=1.8V$, $I_{OUT}=0.5A$, $C_{IN}=1\mu F$, $C_{OUT}=2.2\mu F$)



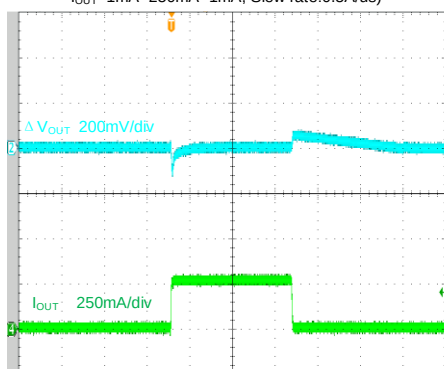
Time (400μs/div)

Shutdown from V_{IN}
($V_{IN}=V_{EN}=3.3V$, $V_{OUT}=1.8V$, $I_{OUT}=0.5A$, $C_{IN}=1\mu F$, $C_{OUT}=2.2\mu F$)



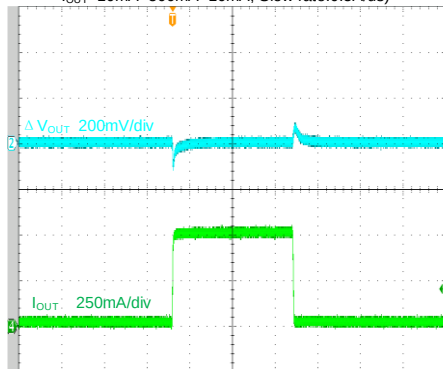
Time (4ms/div)

Load Transient
($V_{IN}=3.3V$, $V_{OUT}=1.8V$, $C_{IN}=1\mu F$, $C_{OUT}=2.2\mu F$, $C_{FF}=100pF$,
 $I_{OUT}=1mA \sim 250mA \sim 1mA$, Slew rate: 0.5A/us)



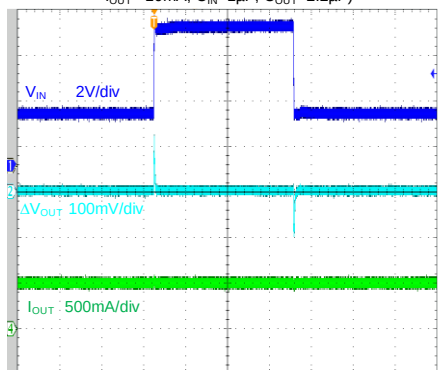
Time (40μs/div)

Load Transient
($V_{IN}=3.3V$, $V_{OUT}=1.8V$, $C_{IN}=1\mu F$, $C_{OUT}=2.2\mu F$, $C_{FF}=100pF$,
 $I_{OUT}=10mA \sim 500mA \sim 10mA$, Slew rate: 0.5A/us)



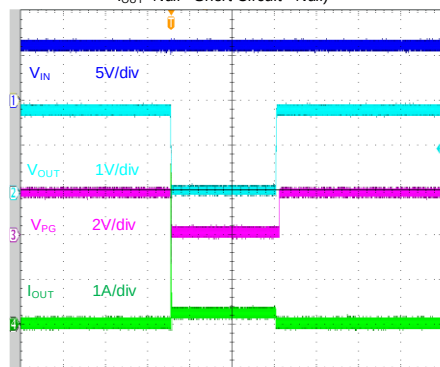
Time (40μs/div)

Line Transient
($V_{IN}=2.3V \sim 6V \sim 2.3V$, Slew rate: 1V/us, $V_{OUT}=1.8V$,
 $I_{OUT}=10mA$, $C_{IN}=1\mu F$, $C_{OUT}=2.2\mu F$)

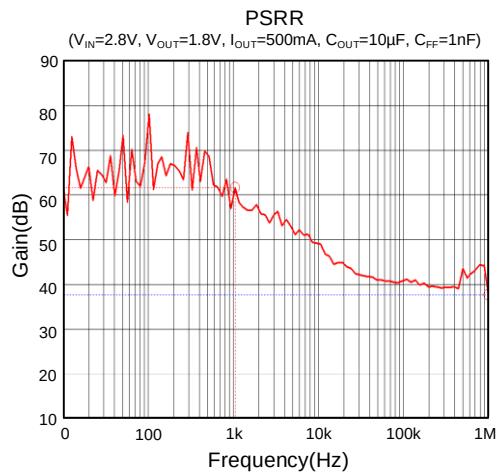
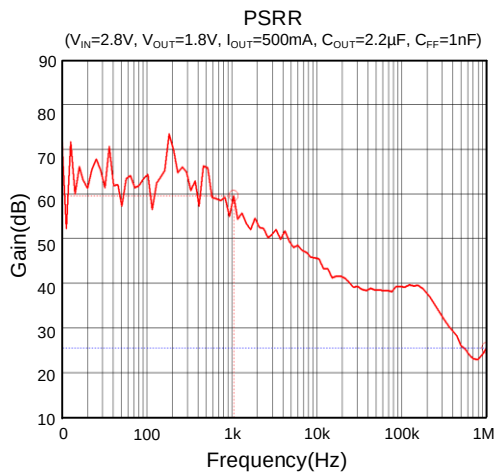
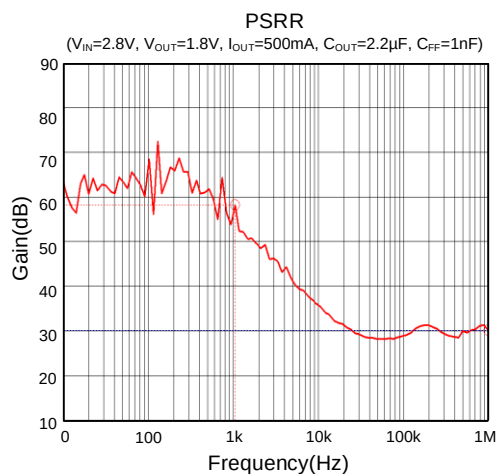
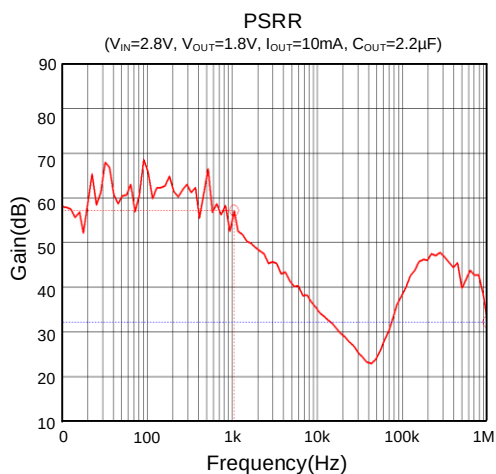


Time (400μs/div)

Short Circuit Protection
($V_{IN}=6V$, $V_{OUT}=1.8V$, $C_{IN}=1\mu F$, $C_{OUT}=2.2\mu F$,
 $I_{OUT}=Null \sim Short\ Circuit \sim Null$)



Time (2ms/div)



Detailed Description

General Features

Input Under Voltage Lock-Out (UVLO)

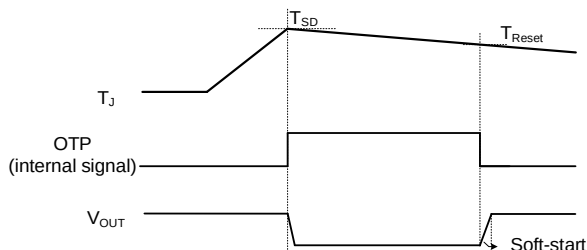
To prevent operation before all internal circuitry is ready, the device remains in a shutdown state until V_{IN} exceeds the UVLO (rising) threshold. Once this threshold is met and EN is active, the device initiates a soft-start ramp. If V_{IN} subsequently falls below the UVLO falling threshold (defined as $V_{IN, UVLO}$ minus the UVLO hysteresis) the device shuts down again.

Enable Function (EN)

The enable pin for the SA21308B is active high. The output voltage is enabled when the enable pin voltage exceeds $V_{EN(HI)}$ and disabled when the enable pin voltage falls below $V_{EN(LO)}$. If independent control of the output voltage is not required, connect the enable pin to the input.

Over-Temperature Protection (OTP)

The SA21308B includes over-temperature protection (OTP) circuitry to prevent overheating due to excessive power dissipation. This will turn off the device when the junction temperature exceeds 170°C . Once the junction temperature cools down by approximately 15°C the device will resume normal operation.



Over-Current Limit and Short-Circuit Protection (OCL&SCP)

The device includes over current limiting and output short-circuit protection. The current limitation circuit regulates the output current to its limitation threshold (I_{CL}) to prevent device damage. If V_{OUT} drops below approximately 40% of the OUT set point, the short-circuit protection reduces the output current to the fold-back short-circuit current limit (I_{SC}) to further decrease the power dissipation. Under over current or short-circuit conditions, the power loss of the device is relatively high, potentially triggering thermal protection.

Power Good Function (PG)

The device features an open-drain PG output that goes to high-impedance when the feedback voltage (V_{FB}) exceeds the power good high threshold (PG_{HTh}). Conversely, PG is pulled low when the V_{FB} drops below

the power good low threshold (PG_{LTh}). PG is an open-drain output, requiring a pull-up resistor (typically between $10\text{ k}\Omega$ and $100\text{ k}\Omega$) connected to a stable active supply voltage rail. Additionally, PG is pulled low if the device encounters other fault conditions such as OTP and UVLO.

Input Capacitor C_{IN}

For normal operation, it is recommended to place a $1\mu\text{F}$ low-ESR ceramic capacitor (X7R grade or better) close to the IN and GND pins. Using a larger input ceramic capacitor can help improve noise immunity as well as improve power-supply rejection ratio (PSRR) and transient response. Care should be taken to minimize the loop area formed by C_{IN} and the IN/GND pins.

Output Capacitor C_{OUT}

For stable operation across the entire temperature range, a minimum of $2.2\mu\text{F}$ low-ESR ceramic capacitor is recommended. Use larger output capacitor values such as $10\mu\text{F}$ to reduce noise, improve load-transient response and enhance PSRR. Some ceramic dielectrics exhibit significant variations in capacitance and equivalent series resistance (ESR) with temperature.

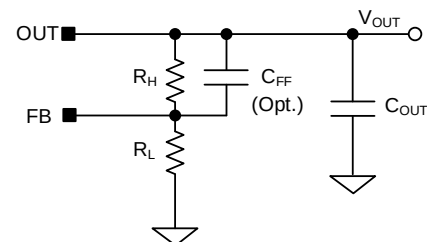
Feedback Resistor Dividers R_H and R_L

Select resistors R_H and R_L to program the proper output voltage. To minimize the power consumption under light loads, choose large resistance values (between $1\text{ k}\Omega$ and $1\text{ M}\Omega$) for both resistors. For example, if V_{OUT} is 1.8 V , and R_H is chosen to be $100\text{ k}\Omega$, then R_L can be calculated using the following equation to be $44\text{ k}\Omega$:

$$R_L = \frac{0.55\text{ V}}{V_{OUT} - 0.55\text{ V}} \times R_H$$

Feedforward Capacitor (C_{FF})

The SA21308B integrates compensation components to achieve good stability and transient response. In some applications, adding a small ceramic capacitor (with a typical value between 10 pF and 1 nF) in parallel with R_H may further enhance the load transient response, therefore, it is recommended for applications with significant load transient step requirements.



Dropout Voltage

The SA21308B features a very low dropout voltage attributed to the extra low $R_{DS(ON)}$ of the main PMOS, which determines the minimum usable supply voltage.

$$V_{DROPOUT} = V_{IN} - V_{OUT} = R_{DS(ON)} \times I_{OUT}$$

Thermal Design Considerations

The SA21308B can deliver a current of up to 500mA over the full operating temperature range. However, the maximum output current must be derated when operating at a higher ambient temperature. Across all possible conditions, the junction temperature must be within the range specified under operating conditions. Power dissipation can be calculated based on the output current and the voltage drop across the regulator.

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT} + V_{IN} \times I_{GND}$$

Maximum power dissipation depends on the thermal resistance of the device package, the PCB layout, the surrounding airflow, and the difference between the junction and ambient temperatures. The maximum power dissipation may be calculated by the following thermal equation:

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

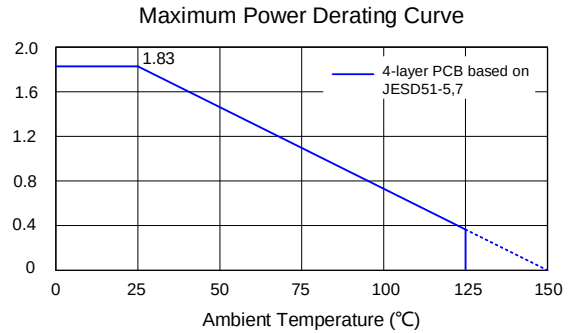
Where $T_{J(MAX)}$ is the maximum junction temperature, T_A is the ambient temperature, and θ_{JA} is the junction to ambient thermal resistance.

To comply with the recommended operating conditions, the maximum junction temperature is 150°C, and the junction to ambient thermal resistance θ_{JA} is layout dependent. For the DFN2×2-6 package, the thermal resistance θ_{JA} is 68.0°C/W when measured on a four-layer thermal test board with thermal vias based on JESD51-5,7.

The maximum power dissipation at $T_A=25^\circ\text{C}$ may be calculated by the following formula:

$$P_{D(MAX)} = (150^\circ\text{C} - 25^\circ\text{C}) / (68.0^\circ\text{C}/\text{W}) = 1.83\text{W}$$

The maximum power dissipation depends on the operating ambient temperature for fixed $T_{J(MAX)}$ and thermal resistance θ_{JA} . Use the derating curve in the figure below to calculate the effect of rising ambient temperature on the maximum power dissipation.



Layout Design

For optimal performance of the SA21308B, the following guidelines must be strictly followed:

1. Place the input/output capacitors as close to the device as possible, minimizing the loop formed by these connections to improve transient performance.
2. Keep all power traces as short and wide as possible. The exposed pad should be connected to a large ground copper area and include multiple GND vias to the GND plane for efficient heat dissipation and noise reduction.
3. A 2-layer or 4-layer board is recommended for thermal performance and better current-handling capability.

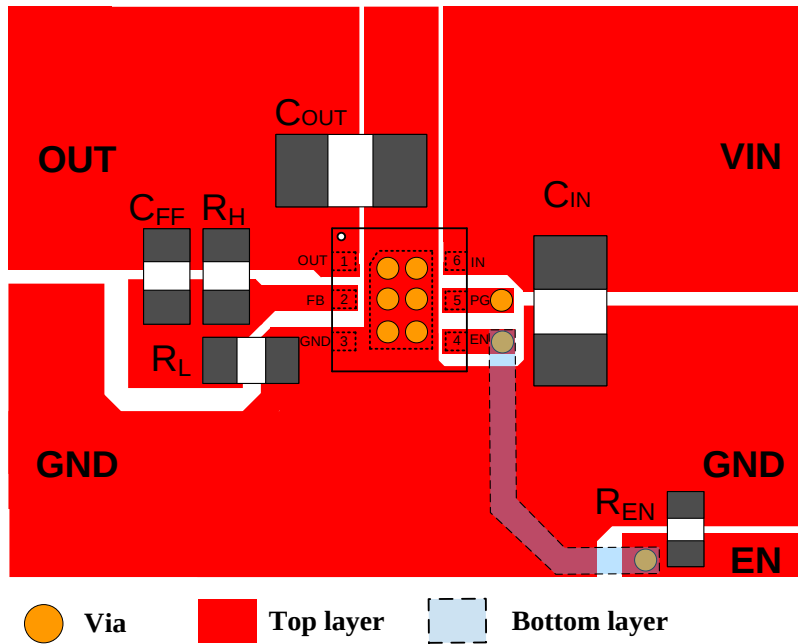
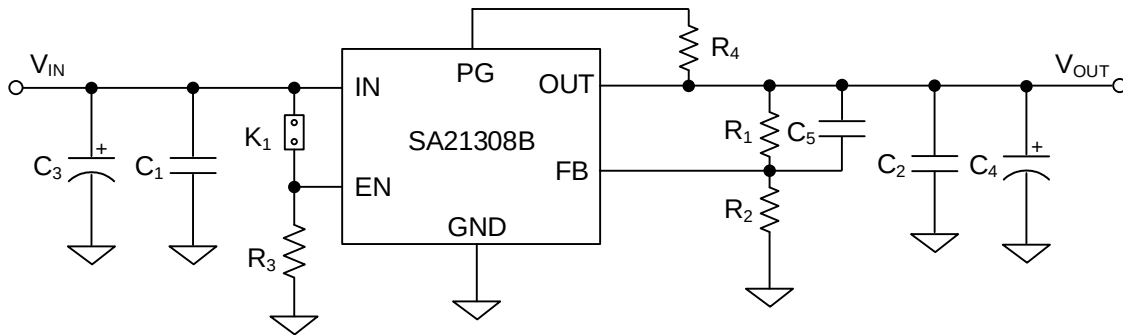


Figure 3. PCB Layout Suggestion

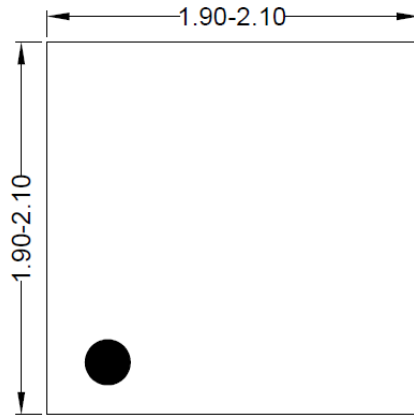
Schematic



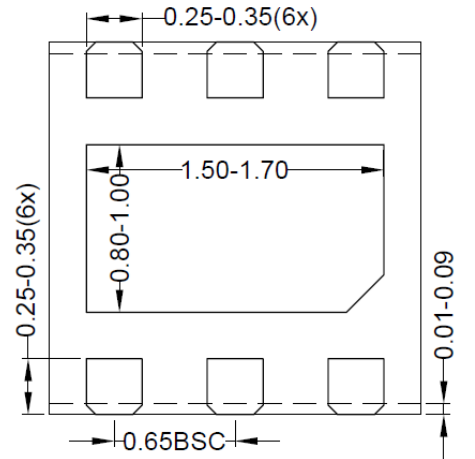
BOM List

Designator	Description	Part Number	Manufacturer
C ₁	1μF/25V/X7R,0805	GRM21BR71E105K	muRata
C ₂	2.2μF/25V/X7R,0805	GRM21BR71E225K	muRata
C ₃ , C ₄	NC		
C ₅	100pF/50V/COG,0603	GRM1885C1H101J	muRata
R ₁	100kΩ, 0603, 1%		
R ₂	44.2kΩ, 0603, 1%		
R ₃	1MΩ, 0603, 1%		
R ₄	100kΩ, 0603, 1%		

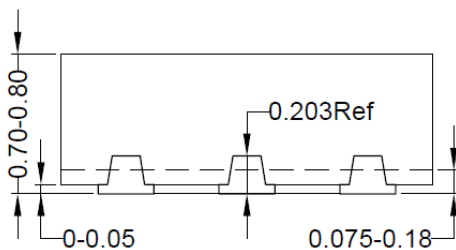
DFN2×2-6 Package Outline



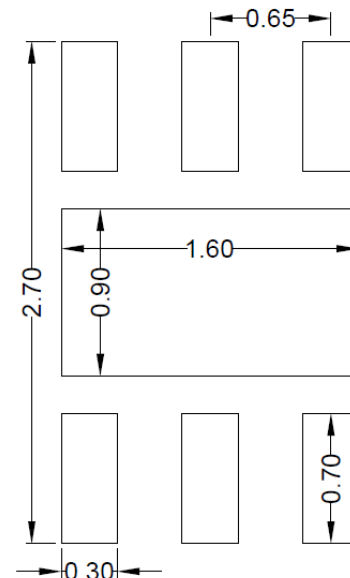
Top View



Bottom View



Front View



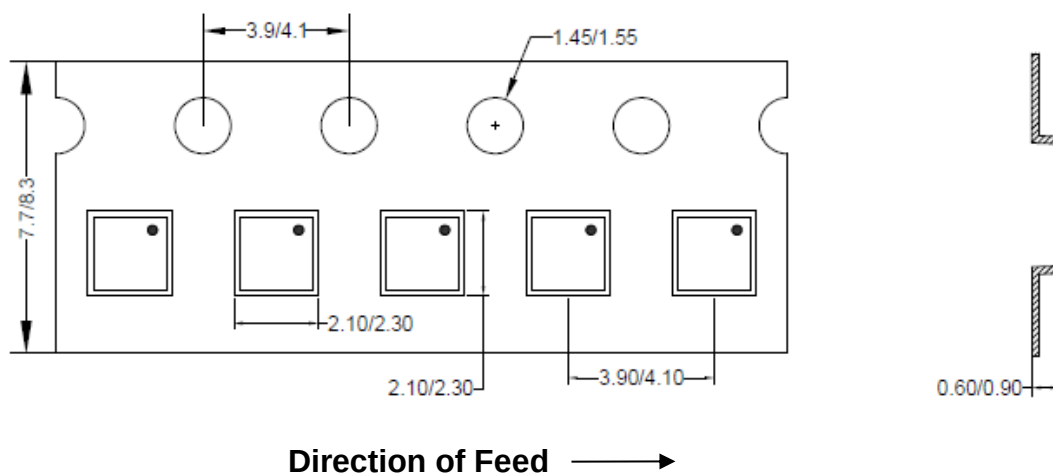
**Recommended PCB Layout
(Reference only)**

Notes: All dimension in millimeter and exclude mold flash & metal burr.

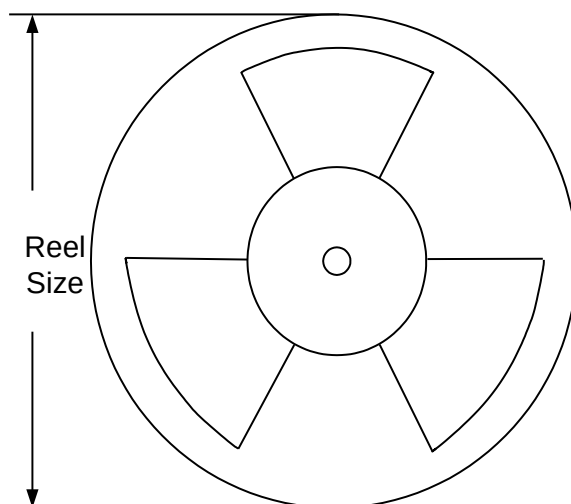
Tape and Reel Information

1. Tape Dimensions and Pin1 Orientation

DFN2×2



2. Reel Dimensions



Package types	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer length(mm)	Leader length (mm)	Qty per reel
DFN2×2	8	4	7	280	160	3000

Revision History

The revision history provided is for informational purposes only and is believed to be accurate; however, not warranted. Please make sure that you have the latest revision.

Date	Revision	Change
May 29, 2025	Revision 1.0	Initial Release

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